

REMARKS

Claims 1-63 are pending in the application, with claims 10, 16, 22, 28, 34 and 40 being independent. Claims 1-39 have been amended and new claims 40-63 have been added. In particular, claim 10 has been amended to recite, as is also recited in claim 16, that the first wiring line includes at least a first portion and a second portion and is formed on a same layer as a gate electrode of a thin film transistor, with each of the portions being connected to the second wiring line through contact holes. Claims 16 and 22 have been amended so as not to require the insulating film to be interposed between the third wiring line and the first and second portions of the first wiring line. Claims 28 and 34 have each been amended to recite that the first wiring line includes first and second portions between which a third wiring line extends, that the second wiring line is along a lengthwise direction of the first wiring line, and that the first and second portions are connected to the second wiring line by contact holes. Claims 14-16, 22, 26-28, 32-34, 38 and 39 have been amended to make minor corrections. Claims 10-39 also have been amended to recite a semiconductor device instead of an integrated circuit, and new dependent claims 46-51 recite that the semiconductor devices are particular types of display devices, as set forth in the specification at page 34, lines 9-14. New claims 52-63 recite particular types of insulating films, as set forth in the specification at page 26, lines 21-23. No new matter has been introduced.

Applicant acknowledges with appreciation the Examiner's allowance of claims 16-27. In allowing the claims, the Examiner notes that the cited prior art does not show:

“the first wiring line having a first portion and second portion where the first portion of the first wiring line and second wiring line are electrically connected to each other via a plurality of contact holes opening in the insulating film and the second portion of the first wiring line and second wiring line are electrically connected to each other via a plurality of contact holes in the opening of the insulating film.”

Applicant notes that Sukegawa (U.S. Patent No. 5,636,329) appears to show this feature in Fig. 3A. However, claims 16-27 are believed to be allowable because Sukegawa, like Takemura

(U.S. Patent No. 5,739,549), does not describe or suggest a third wiring line that is formed on the same surface as the first wiring line and passes between the portions of the first wiring line and across the second wiring line, as recited in each of independent claims 16 and 22, or that the first wiring line is formed on a same layer as a gate electrode of a thin film transistor, as recited in claim 16.

Claim 10 has been rejected as being anticipated by Keizo (JP 5053127). Applicant requests reconsideration and withdrawal of this rejection in view of the amendments to claim 10. In particular, Keizo does not describe or suggest a first wiring line that includes at least a first portion and a second portion and is formed on a same layer as a gate electrode of a thin film transistor, with each of the portions being connected to the second wiring line through contact holes, as recited in amended claim 10.

Dependent claims 11-15 have been rejected as being unpatentable over Keizo in view of Takemura. Applicant requests reconsideration and withdrawal of this rejection because Takemura does not remedy the failure of Keizo to describe or suggest the subject matter of independent claim 10.

Independent claims 28 and 34 have been rejected as being unpatentable over Keizo in view of Shigetoshi (JP 5241200). Applicant requests reconsideration and withdrawal of this rejection in view of the amendments to claims 28 and 34. In particular, neither Keizo, Shigetoshi, nor any proper combination of the two describes or suggests a first wiring line that includes first and second portions between which a third wiring line extends, with the second wiring line being along a lengthwise direction of the first wiring line, and with the first and second portions being connected to the second wiring line by contact holes, as recited in claims 28 and 34.

Dependent claims 29-33 and 35-39 have been rejected as being unpatentable over Keizo in view of Shigetoshi and Takemura. Applicant requests reconsideration and withdrawal of this rejection because Takemura does not remedy the failure of Keizo and Shigetoshi to describe or suggest the subject matter of independent claims 28 and 34.

Similarly to claim 10, new independent claim 40 recites an arrangement in which a second wiring line is formed over a first wiring line that includes at least a first portion and a second portion, and is connected to the first and second portions through contact holes. Accordingly, claim 40 is believed to be allowable over Keizo and the other cited references for at least the reasons discussed above with respect to claim 10.

In addition, claims 10 and 40 are believed to be allowable over Sukegawa at least because Sukegawa does not describe or suggest a second wiring line formed over and connected to portions of a first wiring line that includes a first portion and the second portion. For example, Sukegawa describes an arrangement in which a wiring line that includes two portions (i.e., the first wiring line) is formed over another wiring line (i.e., the second wiring line) such that, in contrast to the recited arrangement of a second wiring line over a first wiring line, Sukegawa describes a first wiring line over a second wiring line.

Applicant submits that all claims are in condition for allowance.

Enclosed is a \$2310 check for request for continued examination fee (\$790), excess claim fees (\$1400) and for the Petition for Extension of Time fee (\$120). Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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